

## **Product Change Notification / MFOL-20FNUC168**

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28-Mar-2022

## **Product Category:**

**Switching Regulators** 

# **PCN Type:**

Manufacturing Change

## **Notification Subject:**

CCB 5062 Initial Notice: Qualification of ABLESTIK ABP 6389 as a new die attach material for selected MIC4684YM and MIC4682YM device families available in 8L SOIC (3.9mm) package at UNIS assembly site.

### **Affected CPNs:**

MFOL-20FNUC168\_Affected\_CPN\_03282022.pdf MFOL-20FNUC168\_Affected\_CPN\_03282022.csv

#### **Notification Text:**

PCN Status:Initial Notification

**PCN Type:**Manufacturing Change

**Microchip Parts Affected:**Please open one of the files found in the Affected CPNs section. Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:**Qualification of ABLESTIK ABP 6389 as a new die attach material for selected MIC4684YM and MIC4682YM device families available in 8L SOIC (3.9mm) package at UNIS assembly site.

#### **Pre and Post Change Summary:**

	Pre Change	Post Change		
	Unisem (M) Berhad	Unisem (M) Berhad		
Assembly Site	Perak, Malaysia	Perak, Malaysia		
	(UNIS)	(UNIS)		
Wire Material	Au	Au		
Die Attach Material	ABLESTIK 84-1LMISR8	ABLESTIK ABP 6389		
Molding Compound Material	G600	G600		
Lead-Frame Material	A194FH	A194FH		
Lead-Frame Paddle Size	95 X 160 MIL	95 X 160 MIL		
DAP Surface Prep	Full spot	Full spot		

#### Impacts to Data Sheet:None

Change Impact:None

**Reason for Change:**To improve manufacturability by qualifying ABLESTIK ABP 6389 as a new die attach material.

## **Change Implementation Status:**In Progress

## **Estimated Qualification Completion Date:**August 2022

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

### Time Table Summary:

	March 2022			>	August 2022						
Workweek	1 0	1	1 2	1 3	1 4		32	33	34	35	36
Initial PCN Issue Date					Х						
Qual Report Availability											Х
Final PCN Issue Date											Х

Method to Identify Change:Traceability code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** 

March 28, 2022: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

### **Attachments:**

PCN\_MFOL-20FNUC168\_Qual Plan.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

#### **Terms and Conditions:**

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our <u>PCN</u> home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the <u>PCN FAQ</u> section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

MIC4684YM

MIC4684YM-TR

MIC4682YM

SPN030027Y

SPN030027Y-TR

MIC4682YM-TR

Date: Sunday, March 27, 2022